

**Amendments to the Specification:**

Please replace the paragraph beginning at page 5, line 16, with the following rewritten paragraph:

As shown in Fig. 3, a first circuit board 350 and a second circuit board 300 are accommodated in a space formed by a metal back cover 40 and a base plate 30 of the plasma display. The second circuit board 300 is secured to the base plate 30 via a plurality of supporters 361 and the first circuit board 350 is secured to the second circuit board 300 via a plurality of supporters 362, such that the second circuit board 300 is separated from the first circuit board 350 by an appropriate distance for bearing an electronic element (the second third electronic element) 340 thereon. The first circuit board 350 is separated from the back cover 40 by supporter 363 to maintain an appropriate distance therebetween for bearing a driver module (the first electronic element) 320 thereon. As the driver module 320 gives out more heat than the electronic element 340, the driver module 320 makes thermal contact with the back cover 40 via a thermal pad 370 (no adhesive) for heat dissipation by means of the large area of the back cover 40. As the back cover 40 is fixed to the first circuit board 350 by a structure including bolts 90 and supporters 363, the thermal pad 370 is pressed tightly between the driver module 320 and the back cover 40 when bolt 90 is mounted to reduce thermal resistance therebetween.

Please replace the paragraph beginning at page 8, line 7, with the following rewritten paragraph:

As shown in Fig. 6, according to the third embodiment, electronic elements 541 are disposed on the back of the circuit board 500 with other elements are the same as in the third

embodiment. In this embodiment, the circuit board 500 divides the space formed by the base plate 30 and the back cover 40 into two subspaces. The driver module 520 and the electronic element 540, both requiring more heat dissipation are disposed in the subspace near the vents 80, 81, and the electronic element 541 (the second electronic element) requiring less heat dissipation is disposed in another subspace.